

104 also corresponds to initializing the timer of the computer to correspond to the running time of the program. Every 1/18th of a second corresponds to one count in the timer. Therefore, the counter which is initialized at the beginning of the call of the program to zero is incremented by one at every 1/18th second time interval. Block 104 corresponds to setting up of the following interrupts which are used during the running of the control system. Set system timer interrupt to point to a subroutine which counts events. When sufficient counts have been received to allow an event (e.g. plot the data on the screen) a flag is set in the interrupt routine, which is then read and acted on accordingly by the program during normal operation. After execution of the interrupt subroutine, program execution resumes at the point at which the interrupt

Details Text Image HTML KWIC

	U	1	Document ID	Issue Da	Page	Current O	Current XR	
1			US 20030123	20030703	78	382/104		System f
2			US 20030123	20030703	79	382/104		System f
3			US 20010011	20010802	39	713/200		Secure m
4			US 6587573	20030701	78	382/104	340/930	System f
5			US 6413616	20020702	42	428/167	428/168	Building
6			US 6412072	20020625	36	713/200		Parasiti
7			US 6219789	20010417	37	713/200		Micropro
8			US 6165562	20001226	42	427/421	427/280	Building
9			US 6150645	20001121	37	219/715	219/702	Radiatio
10			US 6097019	20000801	44	219/750	219/702	Radiatio
11			US 6097006	20000801	20	219/497	399/69	Fixing u
12			US 6094292	20000725	43	359/265	359/267	Electroc
13			US 5953556	19990914	20	399/66		Electrop
14			US 5837978	19981117	29	219/702	219/705	Radiatio
15			US 5832207	19981103	39	713/200		Secure m
16			US 5565737	19961015	6	315/111.2	315/111.41	Aliasing
17			US 5460661	19951024	9	148/251	427/195	Process
18			US 5385796	19950131	31	430/64	430/126	Electrop

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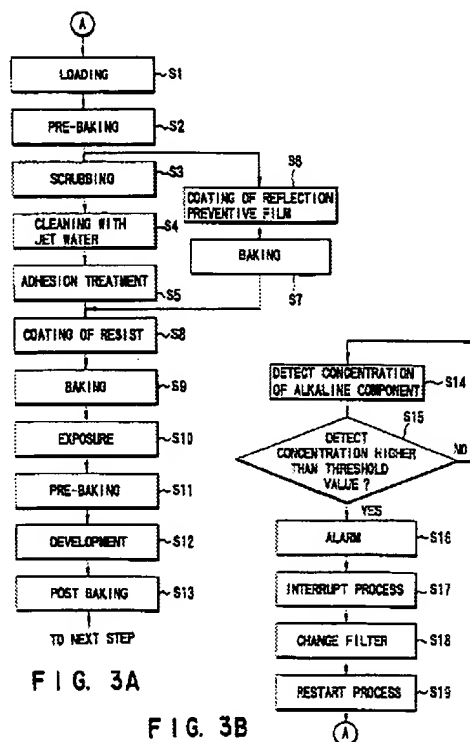


FIG. 3A

FIG. 3B

protective film to the wafer W, while the resist coating unit 15b applies photoresist to the wafer W. The developing section 20 is formed adjacent to the interface section 30 and has two developing units 22. Each of the developing units 22 develops the wafer W subjected to the exposing process in an exposing unit 40.

Detailed Description Text - DETX (18):

The CPU 60 feedback-controls the conveying machine 6 of the coating unit 10 and a drive motor 17 of a spin chuck 16. In accordance with a program transferred from the CPU 60, the process can be continued or interrupted.

Detailed Description Text - DETX (20):

Initially, the wafer moving mechanism 2 takes out a non-processed wafer W from the first cassette 1a of the cassette station 4 in a loader/unloader section, and then places the non-processed wafer W on the holder 3 while centering the wafer W. The main conveying machine 6 picks up the wafer W from the holder 3 by the arm 7 and holds the same to introduce the wafer W into the processing section (step S1). Then, the main conveying machine 6 introduces

U	1	Document ID	Issue Da	Page	Current O	Current XR	
37	□	US 6197418	20010306	7	428/332	427/108	Electroc
38	□	US 6194127	20010227	9	430/313	216/102	Resistiv
39	□	US 6162745	20001219	19	438/795	257/E21.02	Film for
40	□	US 6159645	20001212	6	430/25	430/28	Black ma
41	□	US 6144435	20001107	50	349/133	349/122	Liquid c
42	□	US 6124606	20000926	14	257/291	257/386	Method c
43	□	US 6107009	20000822	25	430/331	510/176	Photores
44	□	US 6099980	20000808	7	428/690	257/40	Organic
45	□	US 6097469	20000801	18	355/30	355/31	Method c
46	□	US 6066575	20000523	22	438/782	427/240	Semicond

	Search Text	DBs
1	1 and subroutine	USPAT; US-PGP UB; DERWEN T
2	5 and interrupt\$3	USPAT; US-PGP UB; DERWEN T
3	1 and interrupt same ((plural or parallel) near3 (timers or timing))	USPAT; US-PGP UB; DERWEN T
4	1 and ((plural or parallel) near3 (timers or timing))	USPAT; US-PGP UB; DERWEN T
5	1 and sub adj routine	USPAT; US-PGP UB; DERWEN T
6	(algorithm or program) near4 (spin near2 coat\$3 or (develop\$4 or process\$3) near4 (substrate or wafer))	USPAT; US-PGP UB; DERWEN T
7	1 and ((timer or timing) or interrupt\$3)	USPAT; US-PGP UB; DERWEN T
8	(sequencer or computer near3 (program oe instruction or code)) near4 (spin near2 coat\$3 or (develop\$4 or process\$3) near4 (substrate or wafer))	USPAT; US-PGP UB; DERWEN T

	Search Text	DBs
9	29 and ((timer or timing) or interrupt\$3)	USPAT; US-PGP UB; DERWEN T

	Search Text	DBs
1	(processing or develop\$4 or coat\$3) near3 (substrate or wafer or lcd)	USPAT; US-PGP UB; DERWEN T
2	serial near4 (timing or control or process\$3) same (sub adj routines or subroutine)	USPAT; US-PGP UB; DERWEN T
3	5 same interrupt\$3 near6 execut\$3 near4 commend	USPAT; US-PGP UB; DERWEN T
4	5 same interrupt\$3 same execut\$3 near4 commend	USPAT; US-PGP UB; DERWEN T
5	5 and interrupt\$3 same execut\$3 near4 commend	USPAT; US-PGP UB; DERWEN T
6	1 and 21	USPAT; US-PGP UB; DERWEN T
7	1 and 5	USPAT; US-PGP UB; DERWEN T
8	5 and interrupt\$3	USPAT; US-PGP UB; DERWEN T

	Search Text	DBs
9	1 and 33	USPAT; US-PGP UB; DERWEN T
10	5 and interrupt\$3 same subroutine	USPAT; US-PGP UB; DERWEN T
11	1 and interrupt\$3 same subroutine	USPAT; US-PGP UB; DERWEN T
12	1 and timing adj chart	USPAT; DERWEN T
13	45 and interrupt\$3 same subroutine	USPAT; US-PGP UB; DERWEN T
14	45 and interrupt\$3	USPAT; US-PGP UB; DERWEN T